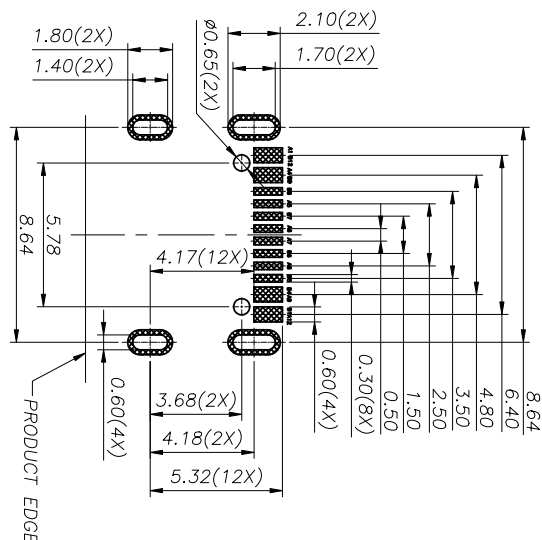
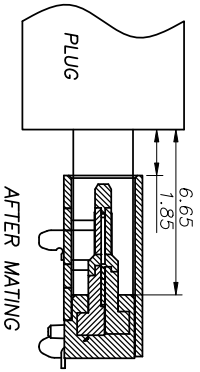
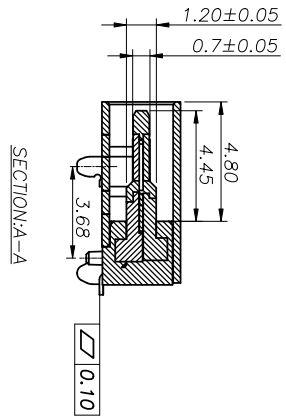
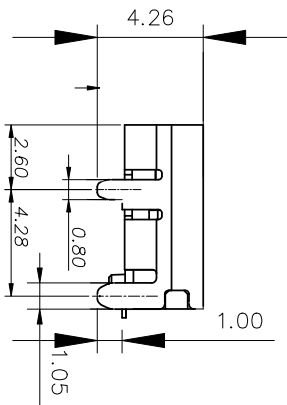
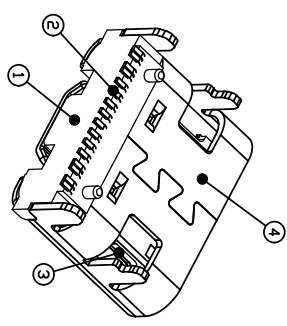
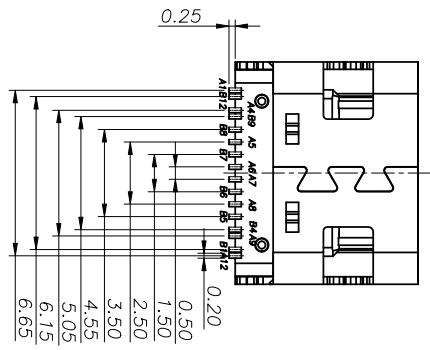
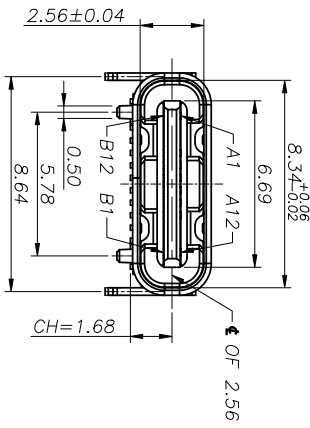
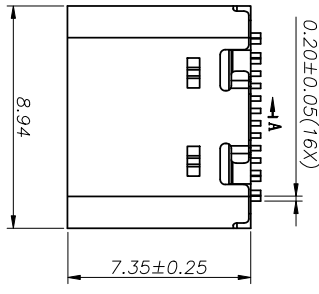


ROHS



RECOMMENDED PCB LAYOUT(TOP VIEW)
THICKNESS: 0.80MM;DEFAULT TOLERANCE:±0.05

- NOTE:
- 1.MATERIAL SPECIFICATION:
1.HOUSING:HIGH TEMPERATURE RESISTANT PLASTIC,UL94 V-0.
2.CONTACTS:COPPER ALLOY
3.MID PLATE: STAINLESS STEEL
4.FRONT SHELL: STAINLESS STEEL
 - 2.PLATING SPECIFICATION:
2-1.CONTACTS:
AU PLATED OVER ALL.
IN 50" MIN. UNDER PLATED OVER ALL.
(GOLD PLATING THICKNESS FOLLOW THE P/N)
PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N
 - 2-2.FRONT SHELL:
IN 30" MIN. UNDER PLATED OVER ALL.
 - 2-3.SHEILD PLATE&MID PLATE:
CLEAR ONLY
 - 3.MECHANICAL PERFORMANCE:
3-1.INSERTION FORCE: 0.5~2.0Nf
3-2.REMOVAL FORCE: 0.8Nf~2.0Nf.
3-3.DURABILITY: 10000 CYCLES.
 - 4.ELECTRICAL PERFORMANCE:
4-1. CURRENT RATING:5.0A
VOLTAGE RATING:5.0V
 - 4-2. LCOR:
VBUS & GND PINS AND OTHER PINS: 40mV/PIN MAX.
SHIELD: 50mV/MAX.
LOR MAX. CHANGE OF ALL PINS: 10mV.
 - 4-3.INSULATION RESISTANCE: 100MΩ MIN
 - 4-4.DIELECTRIC WITHSTAND VOLTAGE:AC 100V FOR 1 MINUTE.
 5. ENVIRONMENTAL PERFORMANCE:
OPERATING TEMPERATURE: -25C~+85C.
 - 6.IR REFLOW:
THE PEAK TEMPERATURE ON THE BOARD SHALL BE MAINTAINED FOR 10 SECONDS AT 260°C.

Signal Name	GND	SSRXp1	SSRXn1	Vbus	SBU2	Dn2	CC2	Vbus	SSTXn2	SSTXp2	GND	
PIN	B12	B11	B10	B9	B8	B7	B6	B5	B4	B3	B1	
Signal Name	GND	SSTXp1	SSTXn1	Vbus	CC1	Dp1	Dn1	SBU1	Vbus	SSRXn2	SSRXp2	GND
PIN	A1	A2	A3	A4	A5	A6	A7	A8	A9	A10	A11	A12

PRODUCT CHART DWG

公差一览表

TOLERANCE UNITS	OTHERWISE
X	±0.35
X	±0.25
XX	±0.20
XXX	±0.02
	°
	±5°
	±2°
	±1°
	±0.5°

深圳市精拓金电子有限公司
Shenzhen Jing Tuo Jin Electronics Co., Ltd.

单位	MM	制图	L S S	制图料号	918-418K202S340043
比例	1:1	审核	G Z F	产品名称	TYPE-C3.1母座板T.35四脚I.07无弹
日期	2020-05-22	核准	黄国荣	PRODUCT NO	MD*SSMT有注16P/IV/LCP黑/3ASH
DATE		APPD		角法	版本
				VER	AD

MAPX	MODIFICATION	DRW	DATE